CLAIMS

1. A laminate type electronic component comprising at least:

a dielectric part containing a dielectric as a constituent material; and

a pair of first and second external electrodes, each disposed in close contact with the dielectric part, opposing each other by way of the dielectric part;

wherein the dielectric part comprises at least two internal electrodes each electrically connected to one of the first and second external electrodes, and at least one dielectric layer made of the dielectric and disposed one by one between electrodes adjacent each other in the at least two internal electrodes;

wherein at least one of the at least two internal electrodes is electrically connected to the first external electrode, and at least one of the at least two internal electrodes is electrically connected to the second external electrode;

wherein each of the first and second external electrodes comprises at least a resin electrode layer made of a conductive resin mainly composed of a thermosetting resin and a conductive particle;

wherein the conductive resin has a conductive particle content of 70 to 75 mass%; and

wherein the conductive particle contains an

acicular particle having an average longitudinal length of 30 to 70 μm and an aspect ratio of 1.5 to 3.3 as a main ingredient.

2. The laminate type electronic component according to claim 1, wherein the acicular particle contained in the conductive resin has a content of 40 to 75 mass% therein.

3. The laminate type electronic component according to claim 1, wherein the conductive particle further contains a spherical particle having an average particle size of 3 to 20 μm;

wherein the acicular particle has a content of 40 to 75 mass% in the conductive particle; and

wherein the spherical particle has a content of 15 to 35 mass% in the conductive particle.

4. The laminate type electronic component according to claim 1, wherein the acicular particle is a particle comprising Ag.

5. The laminate type electronic component according to claim 1, wherein the spherical particle is a particle comprising Ag.

6. The laminate type electronic component according to claim 1, wherein each of the first and second external electrodes is further provided with a metal electrode layer comprising a metal disposed between the resin electrode layer and dielectric part.

7. The laminate type electronic component according to claim 6, wherein the metal electrode layer is formed by sintering a paste mainly composed of any of metals of Cu, Ag, Pd, Ni, and Ag-Pd alloy.

8. The laminate type electronic component according to claim 1, wherein a Ni plating layer formed from Ni by plating is further disposed on an outer surface of the resin electrode layer.

9. The laminate type electronic component according to claim 1, wherein an Sn plating layer formed from Sn by plating is further disposed on an outer surface of the Ni plating layer.

10. The laminate type electronic component according to claim 1, wherein the at least two internal electrodes are disposed in the dielectric part such that one of the two internal electrodes adjacent each other by way of the dielectric layer is electrically connected to the first external electrode whereas the other is electrically connected to the second external electrode.

11. The laminate type electronic component according to claim 1, having an equivalent series resistance value of 40 to 150 mΩ with a standard deviation of 10 mΩ or less in the equivalent series resistance value obtained at the time of operation.

12. The laminate type electronic component

according to claim 10, wherein the standard deviation of the equivalent series resistance value is 8 mΩ or less.